

IN THE UNITED STATES PATENT AND TRADE MARK OFFICE

In re the Application of

Konecni et al.

Serial No.: 08/988,686

Filed: 12/11/97

For: **METHOD AND SYSTEM FOR SELECTIVELY COUPLING A CONDUCTIVE MATERIAL TO A SURFACE OF A SEMICONDUCTOR DEVICE**

Docket No.: TI-22166

Art Unit: 2823

Examiner: Eaton, K.



A.F. #2823 \$
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Assistant Commissioner
for Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that the above correspondence is being
deposited with the U.S. Postal Service as First Class Mail in an
envelope addressed to: Assistant Commissioner of Patents,
Washington, D.C. 20231 on **March 20, 2000**
Jeff Quan

Dear Sir:

Applicant hereby appeals to the Board of Patent Appeals from the decision of the Primary Examiner dated **11/23/99** all rejected claims.

The item(s) checked below are appropriate:

1. ☒ An extension of time to respond to the final rejection

_____ was granted on _____

☒ is requested for 1 month(s).

2. ☐ A timely-response to the final rejection has been filed, as provided in 841 O.G. 1411.

3. ☒ Fee \$300.00:

_____ Not required (*Fee paid in prior appeal*)

☒ The Commissioner is hereby authorized to charge any fees which may be required, or credit any overpayment to Deposit Account No. 20-0668. An original and two copies of this sheet are enclosed.

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Signature [Rule 191(b)]

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